



Title of Change:	Final PCN for assembly and final test site addition SPEL Semiconductor Limited.																																																
Proposed first ship date:	20 April 2016																																																
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>																																																
Samples:	Contact your local ON Semiconductor Sales Office																																																
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>.																																																
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.																																																
Change Part Identification:	Affected products will be identified with the representation of month date code. <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td></td><td>ON Seremban</td><td>SPEL semiconductor</td></tr> <tr> <td>Month date code</td><td style="text-align: center;">M</td><td style="text-align: center;">M</td></tr> </table>					ON Seremban	SPEL semiconductor	Month date code	M	M																																							
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Change category:	☐ Wafer Fab Change ☒ Assembly Change ☒ Test Change ☐ Other _____																																																
Change Sub-Category(s):	☒ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☐ Material Change ☐ Product specific change ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other: _____																																																
Sites Affected:	☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) : ☒ External Foundry/Subcon site(s) SPEL Semiconductor Limited																																																
Description and Purpose: This is a Final Process Change Notification to announce the addition of SPEL Semiconductor Limited as an assembly and final test site for the impacted device. The currently qualified assembly and final test site of ON Semiconductor Seremban, Malaysia will also continue to be used for this device. SPEL Semiconductor Limited is located in Chennai, India, and has obtained ISO9001 certification.																																																	
Reliability Data Summary: <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr style="background-color: #92d050;"> <th>Test</th><th>Specification</th><th>Condition</th><th>Interval</th><th>Results</th></tr> </thead> <tbody> <tr> <td>HTRB</td><td>JESD22-A108</td><td>Ta=150°C, 100%, VDSS=30V</td><td>1008 hrs</td><td>0/77*3lots</td></tr> <tr> <td>HTSL</td><td>JESD22-A103</td><td>Ta=150°C</td><td>1008 hrs</td><td>0/77*3lots</td></tr> <tr> <td>TC</td><td>JESD22-A104</td><td>Ta= -55°C to +150°C</td><td>1000 cyc</td><td>0/77*3lots</td></tr> <tr> <td>H³TRB</td><td>JESD22-A110</td><td>85°C, 85% RH, 80%, VDSS=30V</td><td>1008 hrs</td><td>0/77*3lots</td></tr> <tr> <td>AC</td><td>JESD22-A118</td><td>121°C, 100% RH, 2.03×10⁵Pa, unbiased</td><td>96 hrs</td><td>0/77*3lots</td></tr> <tr> <td>PC</td><td>J-STD-020 JESD-A113</td><td>MSL 1 @ 260°C</td><td></td><td></td></tr> <tr> <td>RSH</td><td>JESD22- B106</td><td>Ta = 265C, 10 sec</td><td></td><td>0/30*3lots</td></tr> <tr> <td>SD</td><td>JSTD002</td><td>Ta = 245C, 10 sec</td><td></td><td>0/30*3lots</td></tr> </tbody> </table>					Test	Specification	Condition	Interval	Results	HTRB	JESD22-A108	Ta=150°C, 100%, VDSS=30V	1008 hrs	0/77*3lots	HTSL	JESD22-A103	Ta=150°C	1008 hrs	0/77*3lots	TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/77*3lots	H ³ TRB	JESD22-A110	85°C, 85% RH, 80%, VDSS=30V	1008 hrs	0/77*3lots	AC	JESD22-A118	121°C, 100% RH, 2.03×10 ⁵ Pa, unbiased	96 hrs	0/77*3lots	PC	J-STD-020 JESD-A113	MSL 1 @ 260°C			RSH	JESD22- B106	Ta = 265C, 10 sec		0/30*3lots	SD	JSTD002	Ta = 245C, 10 sec		0/30*3lots
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**Electrical Characteristic Summary:**

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
TF412ST5G	TF412T5G